Process Equipment C-Flow

For Heat-Seal Bonding, Reflow soldering, ACF Laminating and Heat-Staking applications

The C-Flow controller for Bonding/Soldering application stands alone from other pulsed heat controllers with its unique integration of responsive temperature control and useful tools such as displacement monitoring and force control, all packaged into an easy to use, multi-language, touch screen interface.

Whether you require a system for Heat-Seal Bonding, Reflow soldering, ACF Laminating, Heat-Staking, or other demanding application, the C-Flow can get the job done. The C-Flow was designed from the ground up for easy stand-alone applications and complete factory integration with RS-485, compact size, and external I/O.

C-Flow

The C-Flow is a revolutionary concept in intelligent pulsed heat controllers. The C-Flow is an industry first, by combining precision temperature control with micron level displacement monitoring and real time control of thermode pressure, providing its users with capabilities usually requiring multiple pieces of equipment.

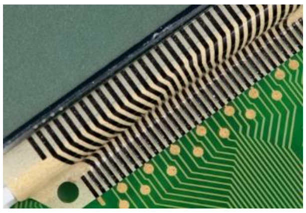
Features

- Process control limited including peak and
- Values Displacement monitoring
- Multi-language user friendly touchscreen interface
- Data output to PC via RS-485
- Process alarms and counters
- Easily integrated into production line

- Easily adjust up to 200 heating profiles!
- Each profile can store up to 20 points for temperature, time and force

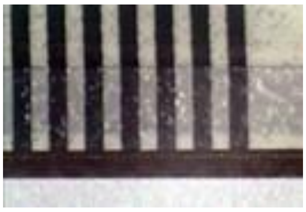
→ Benefits

- Increases part yield and consistency average
- Control your joining connections the best
- Easily transfer of proven processes globally
- For easy Quality Assurance and SPC collection
- Increases part yield and consistency
- Faster transition time from development to production cycles
- Ideal for high mix environments
- Detailed control for challenging applications



Heat Seal Bonding application

Reflow Soldering application



ACF Laminating application

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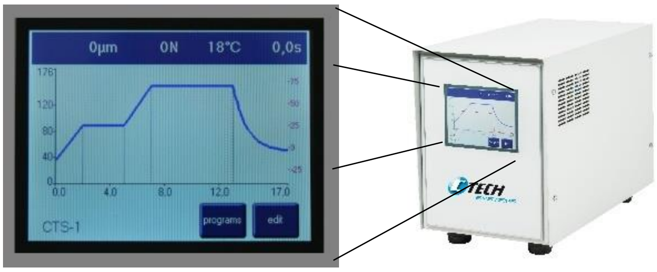
Specifications

C-Flow process equipment		
C-Flow	Dimensions (HxWxD)	310 x 225 x 415 mm
	Power Connection	Power 110/240 VAC, 50 / 60Hz, 6 bar, 16 A
	Transformer	Integrated ‘4 step’ 4.5 kVA Transformer
	Heating profile	200 Heating profiles can be saved
	Per heating profile	20 Programmable points for process time / temperature / force
	Noise level	<70 dB (A)
	Weight	31 kg

C-Flow


0µm ON 18°C 0,0s

Main screen: Graph of the program. The caption shows the displacement of the thermode in micron (option), the force in N (option), and temperature and time.

Programming menu


CTS-1

preheat	35 °C		
step 1	90 °C	2,0 s	100 N
step 2	90 °C	3,0 s	100 N
step 3	150 °C	2,0 s	120 N
step 4	150 °C	6,0 s	120 N
lift	2728 °C		

Steps screen. Each value in each step can be edited. The caption shows the name of the active program


CTS-1

preheat temperature	35 °C
lift temperature	50 °C
power	medium
cooling	on
shown cooling period	4,0 s
temperature upper limit	10 °C
temperature lower limit	10 °C

Globals screen. Each value can be edited. The caption shows the name of the selected program.

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